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(714) 696-5332 – Main Office | www.salesandserviceinc.com


SOLVAY SPECIALTY POLYMERS

- ▶ Gross/Fine Leak Detection Fluid
 - ▶ Thermal Shock Fluid
 - ▶ Liquid Burn-In Test Fluid
 - ▶ Lead Free & Vapor Phase Soldering Fluid
 - ▶ Solef 6008 PVDF Semi-crystalline Thermoplastics
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NORDSON YESTECH AUTOMATED OPTICAL INSPECTION

- ▶ Yestech AOI for Wirebonds and SMT.
 - ▶ Matrix 2D & 3D AXI
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SEMICONDUCTOR EQUIPMENT CORP.

- ▶ Standard & UV Dicing Tapes
 - ▶ Nitto Taping Equipment
 - ▶ Tape Mounters & UV Exposure Systems
 - ▶ Flip Chip Bonders and Manual PnP Systems
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SURON PRECISION TECHNOLOGY

- ▶ Thermal and Heat Transfer Components
 - ▶ Thermal and Getter Lids, Solder Preforms
 - ▶ Carrier and Ceramic Substrates
 - ▶ EMI/RFI Shielding Components
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CAMTEK

- ▶ Sub-micron Defect Wafer Inspection System.
 - ▶ Wafer Inspection for Advanced Interconnect Packaging, Memory, CMOS Image Sensors, MEMS and RF, with Metrology
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MICROPOINT PRO - PRECISION BONDING TOOLS

- ▶ Advanced Wedge Bonding Tools
 - ▶ Die Collets & Vacuum Pick Up Tools
 - ▶ Fluid Dispensing Tools
 - ▶ Custom Micro-Components
 - ▶ Manual Wire Bonders(Wedge, Ball, Dual)
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RGT INC.

- ▶ 6", 8", 12" Wafer Frames
 - ▶ SS Mounting Film Frames
 - ▶ Plastic Film Frames
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KYOCERA INTERNATIONAL INC

- ▶ Electronic Mold Compound
 - ▶ Die Attach Pastes: Conductive & Non-Conductive
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DISCO HI-TEC AMERICA (Baja California)

- ▶ Wafer Grinding
 - ▶ Saw & Laser Singulation
 - ▶ Dicing Blades, Backgrind Tape, Backgrind Wheels
 - ▶ KKM Wafer Processing Services
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NORDSON DAGE X-RAY

- ▶ Dage Quadra 5 & 7 X-Ray Systems
 - ▶ Dage XM8000 Fully Automated Metrology X-Ray
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LASERSSEL corp

- ▶ Laser Compression Bonding
 - ▶ Laser Selective Reflow
 - ▶ Laser Sintering Bonding
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ROKKO SYSTEMS & ROKKO LEADFRAMES PTE LTD.

- ▶ Fully Integrated Package Saw Singulation Systems
 - ▶ Stand-Alone Pick and Place Systems
 - ▶ Custom Tooling & Conversion Kits
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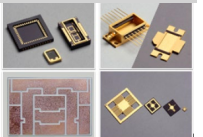
BOSCHMAN ADVANCED PACKAGING TECHNOLOGY

- ▶ Packaging Development
 - ▶ Through Polymer Via Technology
 - ▶ Assembly Services
 - ▶ Film Assisted Transfer Molding
 - ▶ Pressurized Ag Sintering Systems
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ROYCE INSTRUMENTS

- ▶ Bond Testers: Wire Pull / Bond Shear / Die Shear
 - ▶ Die Sorters: Semi & Automated
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NGK ELECTRONICS DEVICES, INC.

- ▶ Multilayer Ceramics
 - ▶ Optical/High Speed Packages
 - ▶ Pressed Ceramics
 - ▶ Electronic Functional Components
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SEPARATION TECHNOLOGISTS (a ResinTech Company)

- ▶ Total Solutions for Industrial Water Recycling.
 - ▶ Closed Loop DI Water, Water Purification, Waste Water Treatment
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